

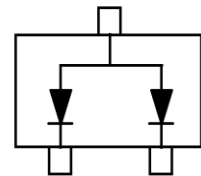
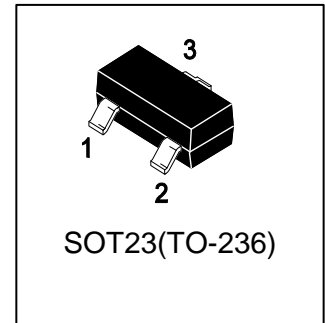
LSTZ5.6NLT1G

S-LSTZ5.6NLT1G

200mW SURFACE MOUNT ZENER DIODES

1. FEATURES

- Planar die construction.
- 200mW power dissipation.
- Ideally suited for automated assembly processes.
- IEC61000-4-2 Air ± 25 KV
Contact ± 25 KV
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LSTZ5.6NLT1G	Z56	3000/Tape&Reel
LSTZ5.6NLT3G	Z56	10000/Tape&Reel

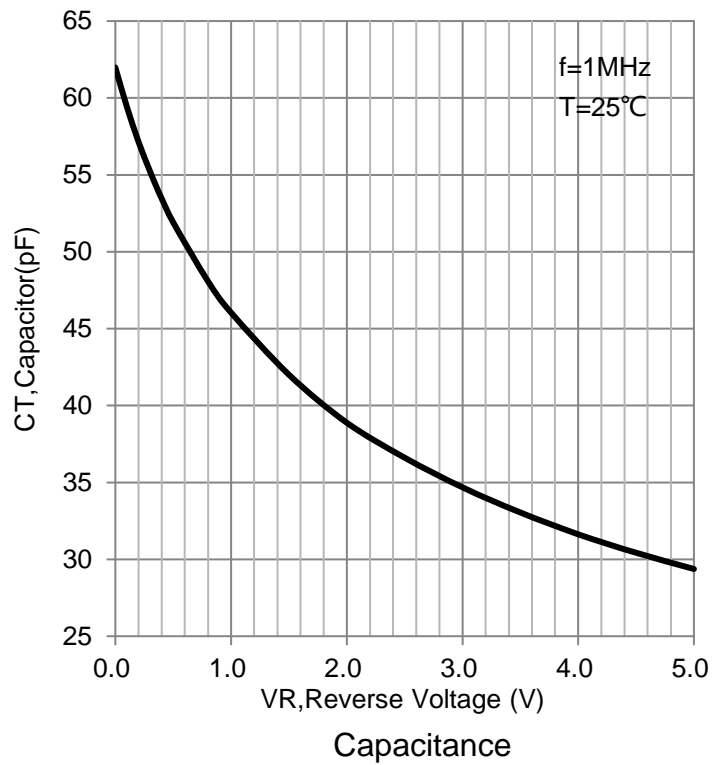
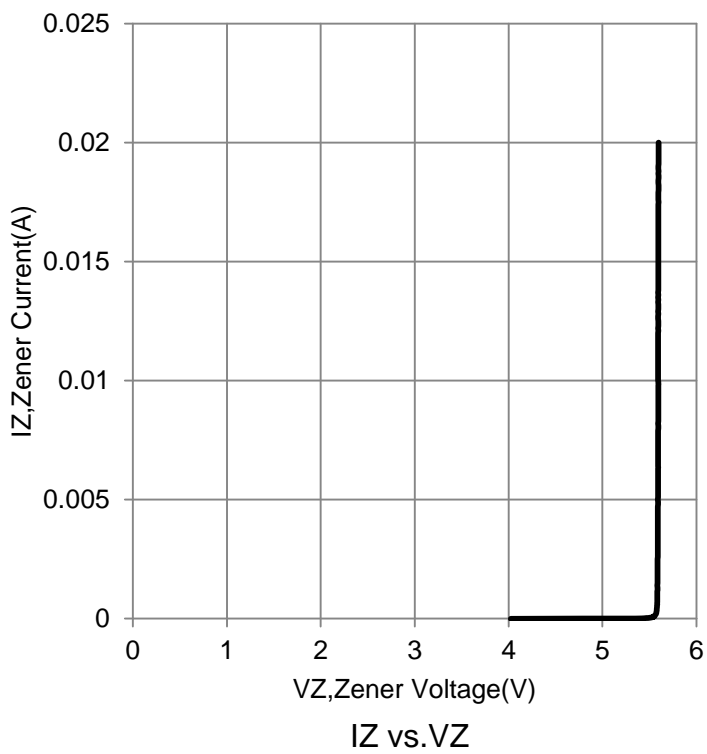
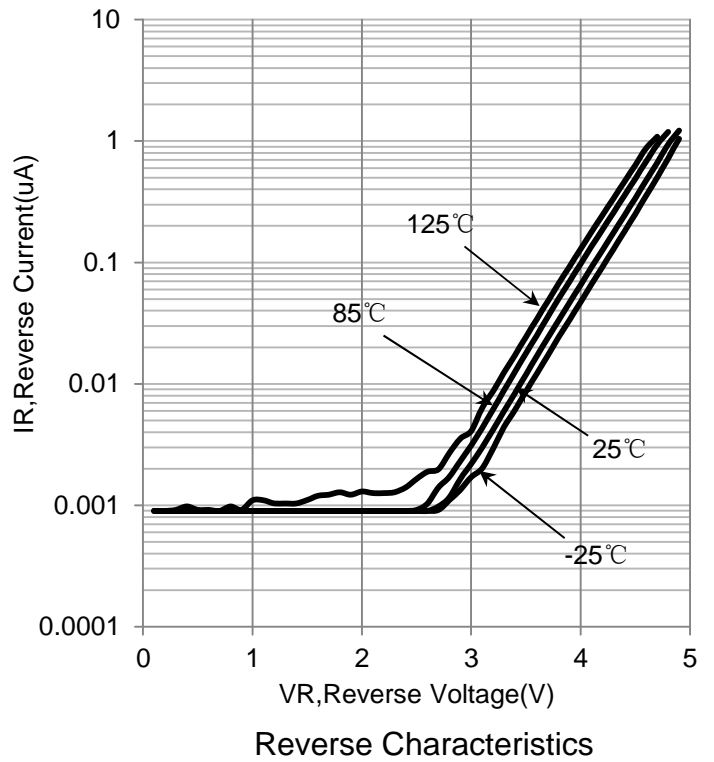
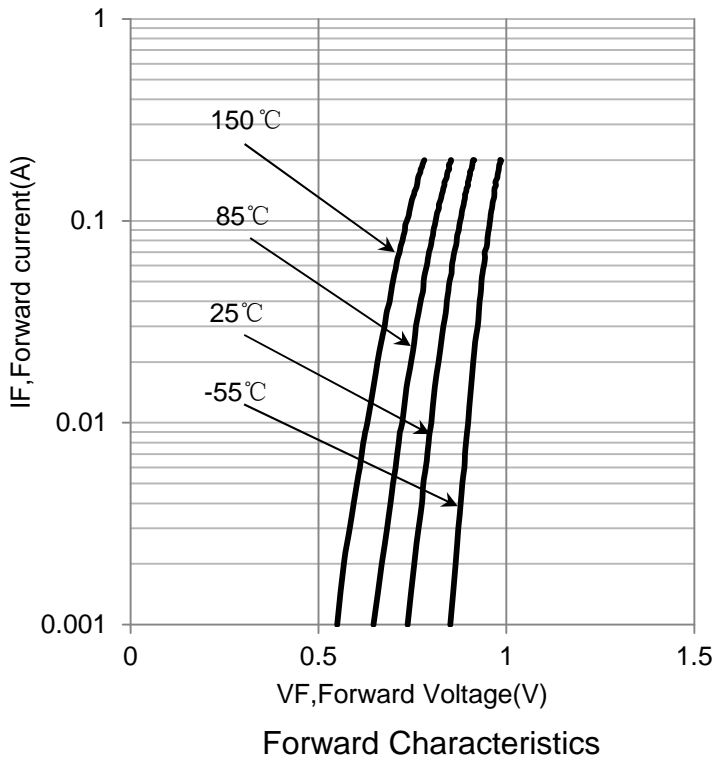
3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Maximum power dissipation	PD	200	mW
Junction temperature	TJ	150	°C
Storage temperature range	Tstg	-55~+150	°C

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Zener voltage (IZ = 5mA)	VZ	5.31	-	5.92	V
Maximum DC reverse current (VR =2.5V)	IR	-	-	1	μA
Dynamic impedance (IZ =5mA)	ZZ	-	-	60	Ω
Rising operation resistance (IZ =0.5mA)	ZZK	-	-	200	Ω
Capacitance between terminals (f=1MHZ,VR =5V)	CT	-	-	35	pF

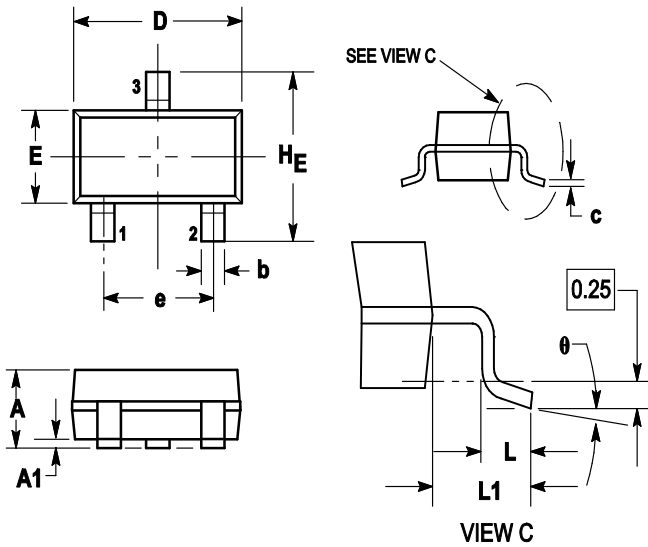
5. ELECTRICAL CHARACTERISTICS CURVES



6. OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

7. SOLDERING FOOTPRINT

